LAMP 2019

HIROSHIMA

Date : **May 21-24, 2019**
Venue : International Conference Center Hiroshima, Hiroshima, Japan
Organizer : Japan Laser Processing Society (JLPS)
Website : http://www.jlps.gr.jp/lamp/lamp 2019/

REGISTRATION & SUBMISSION

Presentation type	Oral / Poster Presentation
Abstract submission	January 18 , 2019, JST
Early registration	February 25, 2019, JST (All presenting authors are required to complete the registrations prior to Early Registration)
Proceedings	Submission due date : May 21.2019（DAY-1) Proceeding of LAMP2019 will be published after the congress. Please submit your manuscript(s) through website. Manuscript Guidelines and Template will be available online.

AIM AND SCOPE

Welcome to LAMP2019!
The International Congress on Laser Advanced Materials Processing (LAMP) deals with science and technology of advanced laser materials processing covering precision microfabrication and high power laser processing. LAMP2019 is held during MAY 21-24, 2019 in Hiroshima, Japan.

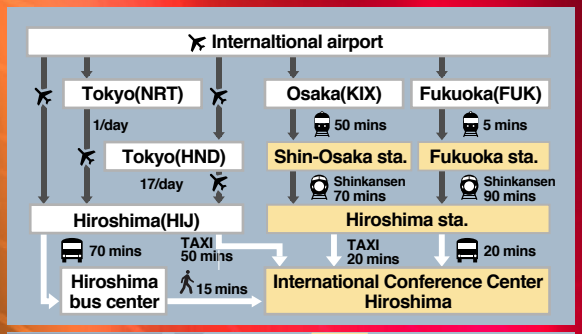
LAMP2019 consists of International Symposia on Laser Precision Microfabrication (LPM) and High Power Laser Processing (HPL) and covers hardware as well as software for fundamental research and industrial applications in both micro and macro processing.

LAMP2019 is planned as a four-day event with a Plenary Session, LPM 20th Year Anniversary Session, Oral and Poster Sessions, Special Sessions dealing with topical issues, and the exhibition with inviting most important world authorities in this field. The aim of this congress is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of laser materials processing, and topics for the next generation with fundamental scientists, end users and laser manufactures.

We expect that LAMP2019 would play an important role not only for understanding fundamental knowledge of laser materials processing but also forecasting future technologies to be developed and the future laser market.

Dr. Koji Sugioka, General Chair, LAMP2019

ACCESS to HIROSHIMA



LAMP2019 Venue, "International Conference Center Hiroshima (ICCH) " is located right next to Hiroshima Peace Memorial Museum in the hallowed ground of Hiroshima Peace Memorial Park. Address: 1-5 Nakajima-cho, Naka-ku, Hiroshima, Japan

VISIT HIROSHIMA WEBSITE

http://visithiroshima.net/plan_your_trip/directions_and_maps.html

CONTACT US

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LAMP2019 Secretariat
Japan Laser Processing Society (JLPS)
c/o JWRI, Osaka University, Japan

LPM TOPICS

1. Fundamental aspects (Dynamics, modeling, simulation, etc.)
2. Process monitoring and control
3. Laser and photochemistry
4. Nanotechnology
5. Laser-based direct-write techniques
6. Ultra-short pulse laser processing
7. VUV laser and X-ray processing
8. Surface treatment (Texturing, cleaning, annealing, modification, etc.)
9. Advanced laser processing (Fiber laser, disc laser, FEL, etc.)
10. Micro-patterning and micro-structuring
11. Nano ripple formation
12. Micro-machining
13. 3-D micro- and nano-fabrication
14. Drilling and cutting
15. Micro-welding and micro-bonding
16. Micro-forming
17. Wafer dicing
18. Marking and trimming
19. Glass/Ceramic processing
20. Packaging and mounting process
21. Lithography (including EUV source and application)
22. Manufacture of micro devices and systems
23. Film deposition and synthesis of advanced materials (PLD, CVD, etc.)
24. Nano- and micro-particles
25. Medical and biological applications
26. Optics and systems for laser microprocessing
27. Laser devices
28. Beam shaping
29. Industrial applications
30. Others
31. LPM Special Session (L1) "Laser synthesis and processing in liquids"
32. LPM Special Session (L2) "Laser coloring using short and ultrashort pulsed lasers"
33. LPM Special Session (L3) "Optics and Glass"

HPL TOPICS

1. Fundamentals of laser-materials interactions
2. Laser-induced plasma/plume
3. Gas laser
4. Solid-state laser (YAG, Fiber, Disk, etc.)
5. Diode laser
6. Green or blue laser
7. Optics
8. Beam delivery system
9. Monitoring and control (including OCT)
10. Metallurgical and mechanical aspects
11. Modeling and simulation
12. Cleaning
13. Surface modification (Hardening, quenching, alloying, etc.)
14. Cladding and rapid prototyping
15. Additive manufacturing (3D Printer)
16. Welding
17. Welding of thick plate
18. Welding of high strength steel
19. Welding of light metals and alloys
20. Joining of plastics, glasses or ceramics
21. Joining of dissimilar materials (plastic to metal)
22. Joining of battery or fuel cell
23. Remote welding
24. Hybrid welding
25. Brazing and soldering
26. Drilling (High speed and high quality)
27. Cutting (of CFRP, etc.)
28. Thick plate cutting and dismantling
29. Industrial applications
30. Innovative applications (Sandwich panel, etc.)
31. Present status and future prospects
32. Others

LAMP 2019

THE 8TH INTERNATIONAL CONGRESS ON LASER ADVANCED MATERIALS PROCESSING